

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Quality improvement for CIPOS™ mini DCB products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **31. December 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD“**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Wolfgang Mayrhuber  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

# Product / Process Change Notification



N° 2016-087-A

► Products affected:	Sales Name	SP N°	OPN	Package
	IKCM15L60GD	SP001370928	IKCM15L60GDXXKMA1	PG-MDIP-24
	IKCM15L60HD	SP001423512	IKCM15L60HDXXKMA1	PG-MDIP-24
	IKCM15R60GD	SP001370934	IKCM15R60GDXXKMA1	PG-MDIP-24
	IKCM20L60GD	SP001299274	IKCM20L60GDXXKMA1	PG-MDIP-24
	IKCM20L60HD	SP001370946	IKCM20L60HDXXKMA1	PG-MDIP-24
	IKCM20R60GD	SP001293434	IKCM20R60GDXXKMA1	PG-MDIP-24
	IKCM30F60GD	SP001271892	IKCM30F60GDXXKMA1	PG-MDIP-24
	IKCM30F60HD	SP001370952	IKCM30F60HDXXKMA1	PG-MDIP-24

## ► Detailed Change Information:

**Subject:** Introduction of selective Ni plated lead frame and second source for mold compound.

**Reason:** Quality improvement at wire bonding and ensuring delivery capability.

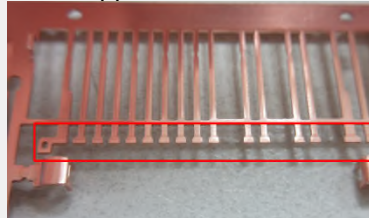
### Description:

#### Old

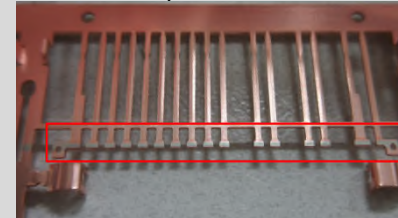
#### New

#### Lead frame

- Bare copper



- Selective Ni plated



#### Mold Compound

- Kyocera

- Kyocera and KCC

## ► Product Identification:

Internal identification ensured by manufacturing code.  
External identification by lot numbers.

## ► Impact of Change:

No influence on electrical parameters or product dimensions.  
Increased shear strength of wire bonds.

## ► Time Schedule:

- Final qualification report:
- First samples available:
- Intended start of delivery:

available on request

on request

01-January-2017, existing stock will be depleted first

If you have any questions, please do not hesitate to contact your local Sales office.